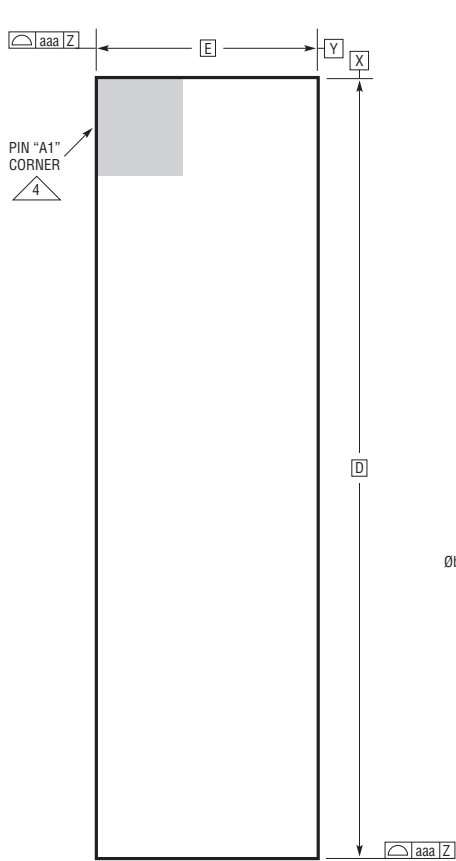
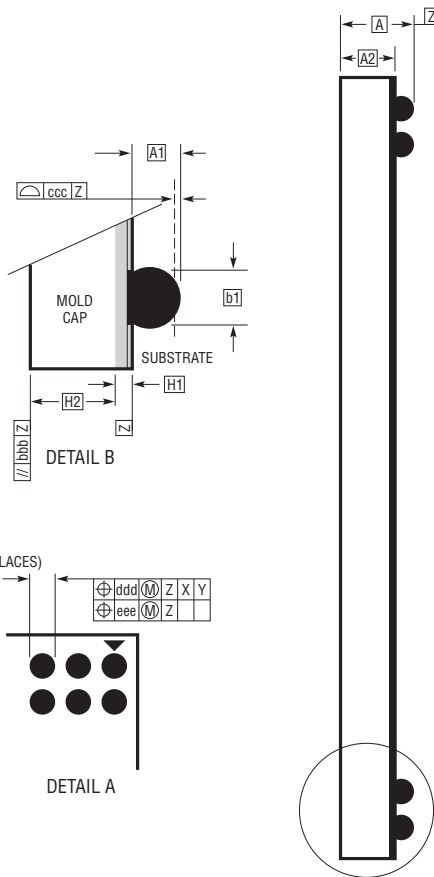


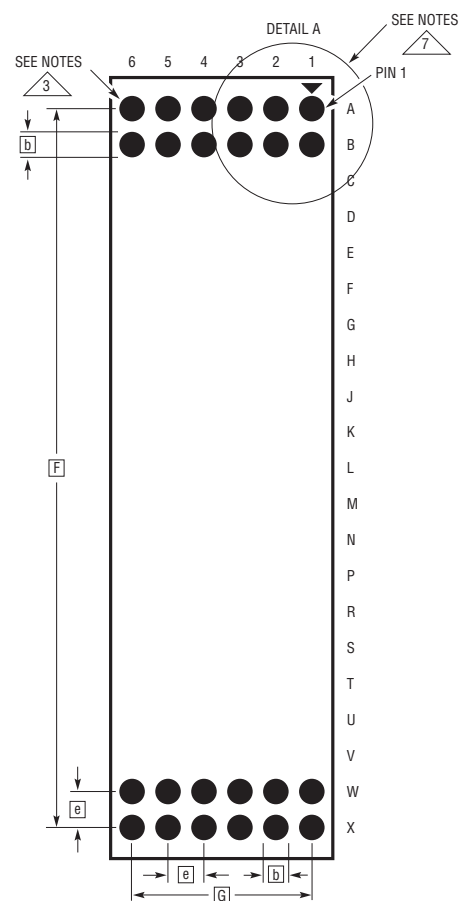
BGA Package
24-Lead (22mm × 6.25mm × 2.06mm)
 (Reference LTC DWG# 05-08-1991 Rev 0)



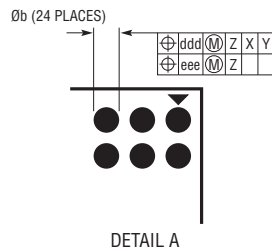
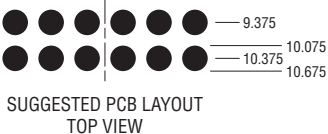
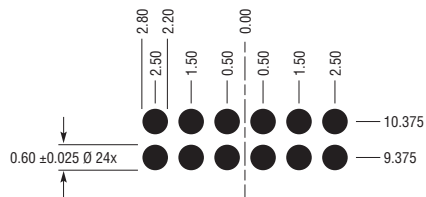
PACKAGE TOP VIEW



DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.81	2.06	2.31	
A1	0.40	0.50	0.60	
A2	1.41	1.56	1.71	
b	0.55	0.60	0.65	
b1	0.45	0.50	0.55	
D		22.0		
E		6.25		
e		1.0		
F		20.75		
G		5.0		
H1	0.46	0.56	0.66	
H2	0.95	1.00	1.05	
aaa			0.15	
bbb			0.10	
ccc			0.15	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 24				

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 3. BALL DESIGNATION PER JESD MS-028 AND JEP95
 4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
 7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

